



# Product Change Notification

**Change Notification #:** 117888 - 00  
**Change Title:** Select Intel® SSD D5-P4320 Series Products, Intel® SSD D5-P4326 Series Products, and Intel® SSD D5-P4420 Series Product PCN 117888-00, Product Design, Add second source DRAM, PI PCB, Inductor, and FET  
**Date of Publication:** November 25, 2020

## Key Characteristics of the Change:

Product Design

## Forecasted Key Milestones:

|                                                                         |                   |
|-------------------------------------------------------------------------|-------------------|
| <b>Date Customer Must be Ready to Receive Post-Conversion Material:</b> | February 24, 2021 |
|-------------------------------------------------------------------------|-------------------|

## Description of Change to the Customer:

The Intel® SSD D5-P4320 Series Products, Intel® SSD D5-P4326 Series Products, and Intel® SSD D5-P4420 Series Product listed in the Products Affected table below will have the following changes:

### Change 1:

The SKUs listed in the table below will have the following change:

| Product Code    | MM#    | Change Detail                                                          |
|-----------------|--------|------------------------------------------------------------------------|
| SSDPE2NV076T801 | 979157 | Add PI PCB, Hynix DRAM, Chilisin Inductor, Nexperia FET as 2nd source. |
| SSDPE2NV076T810 | 979158 |                                                                        |
| SSDPE2NV153T801 | 979184 |                                                                        |
| SSDPE2NU076T801 | 999DXN |                                                                        |

### Change 2:

The SKUs listed in the table below will have the following change:

| Product Code    | MM#    | Change Detail                                                  |
|-----------------|--------|----------------------------------------------------------------|
| SSDPEWNV153T801 | 980943 | Add Hynix DRAM, Chilisin Inductor, Nexperia FET as 2nd source. |
| SSDPEWNV153T810 | 980944 |                                                                |
| SSDPEXNV153T801 | 980945 |                                                                |

## Customer Impact of Change and Recommended Action:

Intel will attempt to deplete pre-conversion material before shipping post-conversion material but there is a possibility of Intel shipping mixed inventory. Therefore, customers will need to manage and migrate to the post-conversion material as soon as possible.

Milestone dates are estimates and subject to change based on business and operational conditions.

\* Other names and brands may be claimed as the property of others.

## Products Affected / Intel Ordering Codes:

| Marketing Name                                                                              | Product Code    | MM#    |
|---------------------------------------------------------------------------------------------|-----------------|--------|
| Intel® SSD D5-P4320 Series (7.68TB, 2.5in, PCIe 3.1 x4, 3D2, QLC) Generic Single Pack       | SSDPE2NV076T801 | 979157 |
| Intel® SSD D5-P4320 Series (7.68TB, 2.5in, PCIe 3.1 x4, 3D2, QLC) Generic 10 Pack           | SSDPE2NV076T810 | 979158 |
| Intel® SSD D5-P4326 Series (15.3TB, 2.5in PCIe 3.1 x4, 3D2, QLC) Generic Single Pack        | SSDPE2NV153T801 | 979184 |
| Intel® SSD D5-P4326 Series (15.36TB, E1.L 9.5mm, PCIe 3.1 x4, 3D2, QLC) Generic Single Pack | SSDPEWNV153T801 | 980943 |
| Intel® SSD D5-P4326 Series (15.36TB, E1.L 9.5mm, PCIe 3.1 x4, 3D2, QLC) Generic 10 Pack     | SSDPEWNV153T810 | 980944 |
| Intel® SSD D5-P4326 Series (15.36TB, E1.L 18mm PCIe 3.1 x4, 3D2, QLC) Generic Single Pack   | SSDPEXNV153T801 | 980945 |
| Intel® SSD D5-P4420 Series (7.68TB, 2.5in, PCIe 3.1 x4, 3D2, QLC) Generic Single Pack       | SSDPE2NU076T801 | 999DXN |

## PCN Revision History:

**Date of Revision:**

November 25, 2020

**Revision Number:**

00

**Reason:**

Originally Published PCN



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**Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.**

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